

Abstract

Provided is a method of preconditioning a resin useful for removal of organic impurities from a hydrogen peroxide solution. The method involves the steps of (a) rinsing the resin with deionized water; (b) contacting the resin with an acid solution; and (c) rinsing the acid treated resin with deionized water. Also provided is a resin preconditioned in accordance with the method, and a method of removing organic impurities from a hydrogen peroxide solution using the preconditioned resin. The invention has particular applicability to the removal of total organic carbon (TOC) impurities from a hydrogen peroxide solution which can be used in the manufacture of semiconductor devices.

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